



Selected papers from the APMM 2019–Active Polymeric Materials and Microsystems Conference

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submissions:
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Message from the Guest Editors

Dear Colleagues,

This Special Issue will publish selected papers from the APMM 2019 – Active Polymeric Materials and Microsystems Conference, 16–19 September, 2019, in Dresden, Germany. The conference is co-organized by Technische Universität Dresden, Germany, and IPF – The Leibniz Institute of Polymer Research Dresden, Germany.

Relevant topics include:

- Electro-active materials;
- Smart gels;
- Hydrogels and microgels;
- Synthesis and characterization, material properties;
- Responsive and adaptive systems;
- Hydrogel-based sensors, actuators, devices, and microsystems;
- Soft robots;
- Microfluidics;
- System integration, additive manufacturing;
- Modelling and simulation.





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Message from the Editor-in-Chief

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